J.E.T. Co., LTD.

Financial Results for the Six Months Ended June 30, 2025

August 25, 2025

Agenda

1. Summary of Financial Results for the Six Months Ended June 30, 2025 and Forecast for the Year Ending December 31, 2025
2. Revision of Management Strategy in Response to the Revised Financial Results

Appendix

1. Summary of Financial Results for the Six Months Ended June 30, 2025 and Forecast for the Year Ending December 31, 2025

Results Summary

**Decrease in revenue due to delay in sales of cleaning equipment to foundries in China and to Japan.
Profit significantly decreased due to the recording of low-margin equipment in the Chinese market and new projects, etc., with many customization elements, and an inventory valuation loss of products for which orders were received but delivery dates were not clear.**

Net sales	Operating profit	Ordinary profit	Net profit
7,280 million JPY	-1,637 million JPY	-1,705 million JPY	-2,450 million JPY
YoY -27.0%	YoY -	YoY -	YoY -

- ✓ **Uncertain conditions continue due to factors such as economic turmoil in China caused by the U.S. trade policy (tariff measures); serious stagnation of the Chinese economy, including sluggish consumption triggered by a real estate downturn and the U.S.-China conflict; and ongoing geopolitical risks.**
- ✓ **Global consumption of electronics products remains stagnant. Especially in the Chinese market, foundry capacity utilization rates have slowed down due to the impact of several years of increased new capital investment in mature semiconductors.**
- ✓ **In the memory business, prices of DRAMs and NAND flash memories rose moderately, and demand for GPUs and HBMs for AI servers remained strong and investment continued.**

Consolidated Results

In addition to the decline in sales, one-time factors (e.g., recording of an inventory valuation loss) also contributed significantly and resulted in a fall into the red.
Net income was a loss of 2,450 million JPY, including a reversal of deferred tax assets of 760 million JPY.

Unit (millions of JPY)	Six months ended June 30, 2024	Sales ratio (%)	Six months ended June 30, 2025	Sales ratio (%)	YoY (%)
Net sales	9,968	-	7,280	-	-27.0%
Gross profit or loss	2,006	20.1%	-295		-
SG&A expenses	1,418	14.2%	1,342	18.4%	-5.4%
Operating profit or loss	587	5.9%	-1,637	-	-
Ordinary profit or loss	520	5.2%	-1,705	-	-
Profit or loss	297	3.0%	-2,450	-	-

Consolidated Balance Sheet

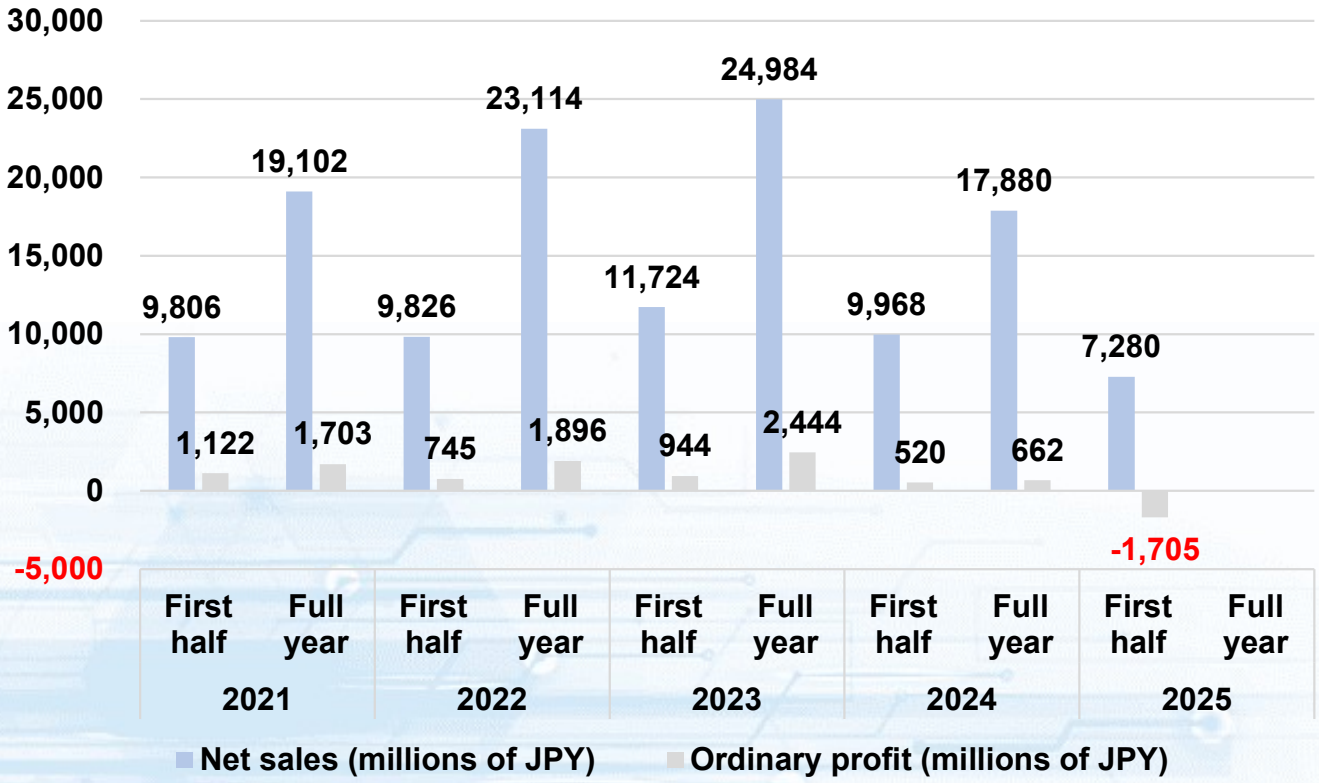
Recording of valuation losses on "Merchandise and finished goods," "Work in progress," and "Raw materials and supplies," which had increased or been in arrears

Unit (millions of JPY)	Fiscal year ended December 31, 2024	Six months ended June 30, 2025	Increase/Decrease	Main factors of change
Current assets	23,824	20,750	-3,073	Decrease in "Merchandise and finished goods," "Work in progress" and "Raw materials and supplies"
Property, plant and equipment	831	800	-31	
Intangible assets	101	107	6	
Investments and other assets	734	118	-616	Decrease in "Deferred tax assets"
Total assets	25,491	21,776	-3,715	
Current liabilities	8,575	7,530	-1,045	Decrease in "Short-term borrowings"
Non-current liabilities	4,446	4,365	-81	Decrease in "Long-term borrowings"
Total liabilities	13,021	11,895	-1,126	
Total net assets	12,469	9,881	-2,588	Decrease in "Retained earnings"
Total liabilities and net assets	25,491	21,776	-3,715	

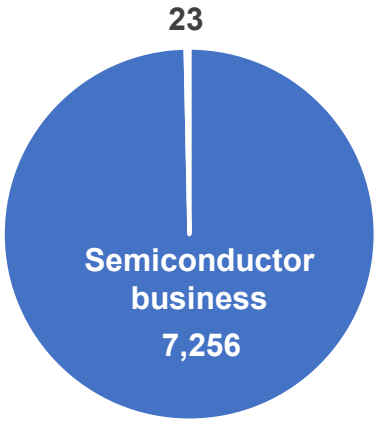
Net Sales and Ordinary Profit and Composition of Net Sales

Ordinary profit fell into the red

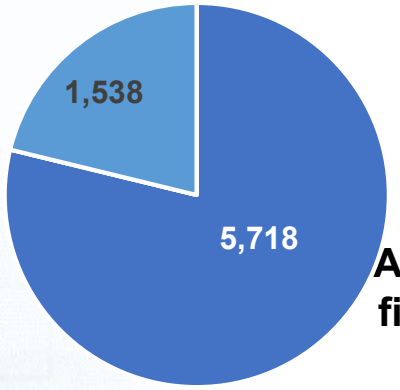
Trends in Net Sales and Ordinary Profit



Consolidated Net Sales by Segment



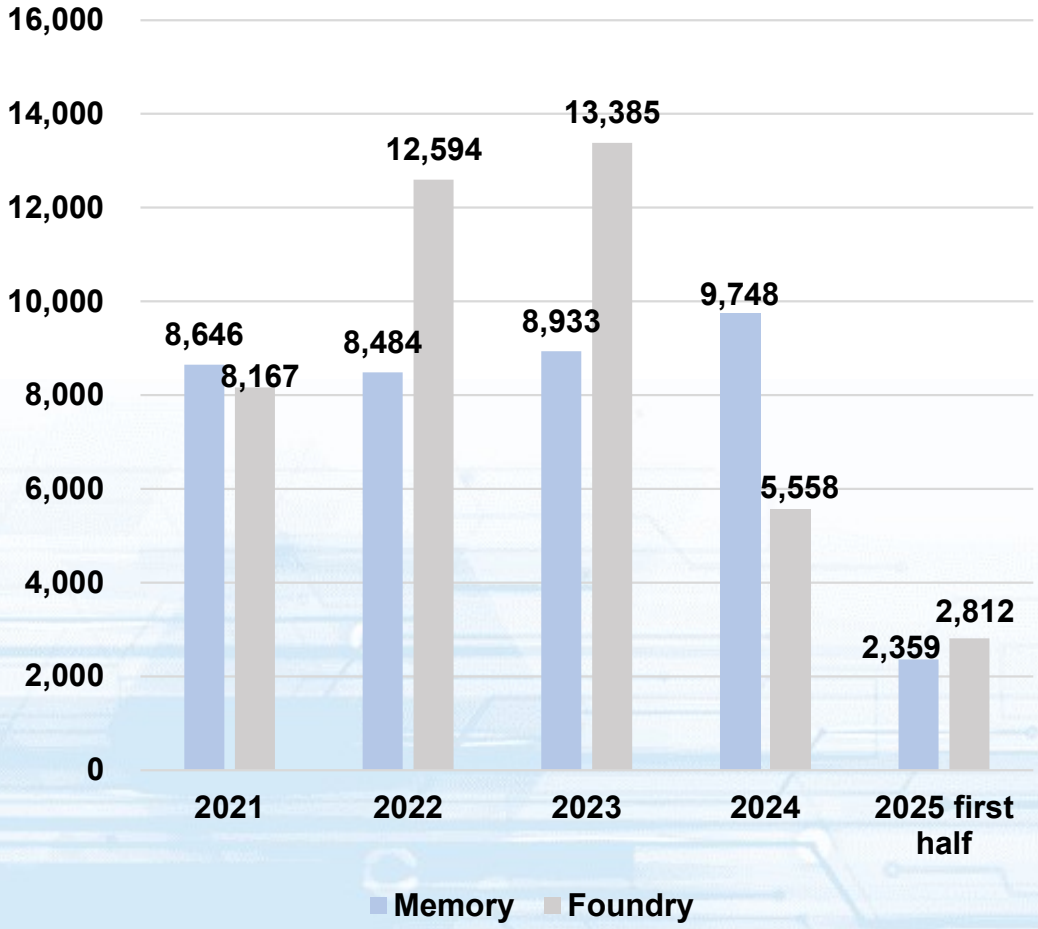
Breakdown of Semiconductor Business



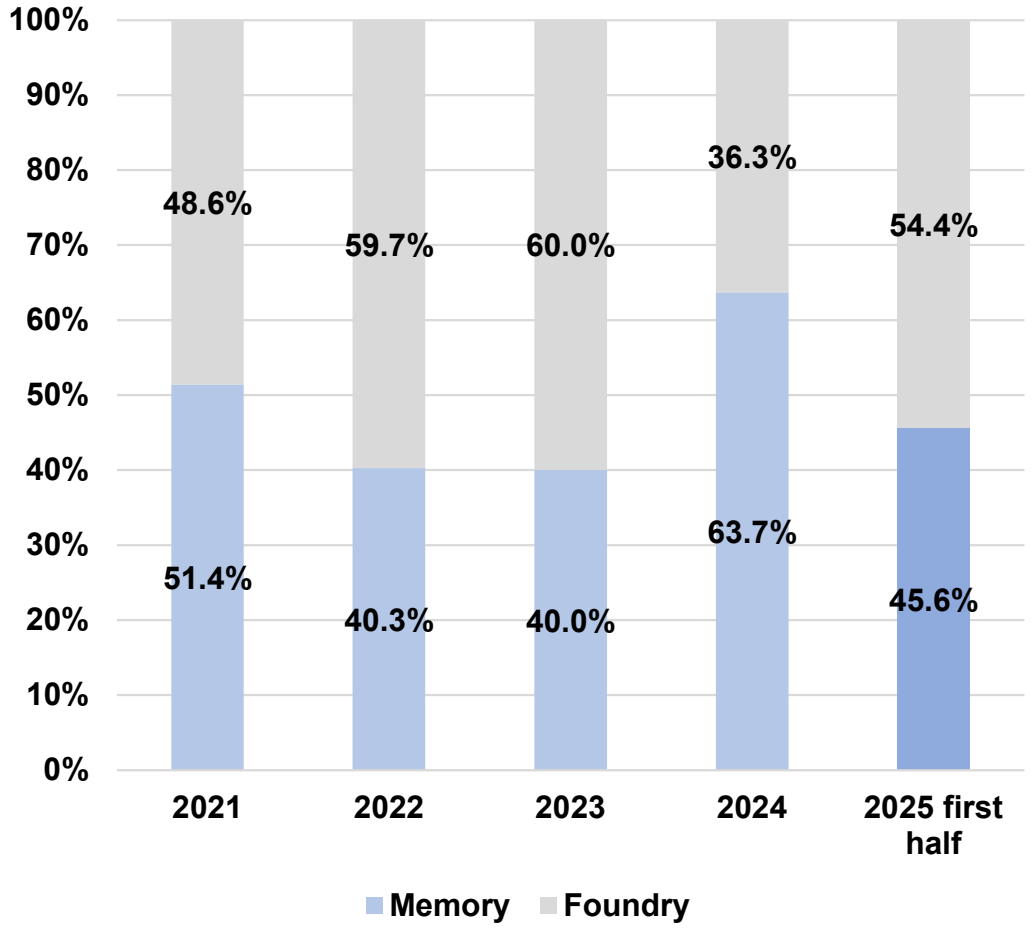
Actual results for the first half of the fiscal year ending December 2025

Trends in Equipment Net Sales (by Shipping Destination)

Trends in Equipment Net Sales by Shipping Destination

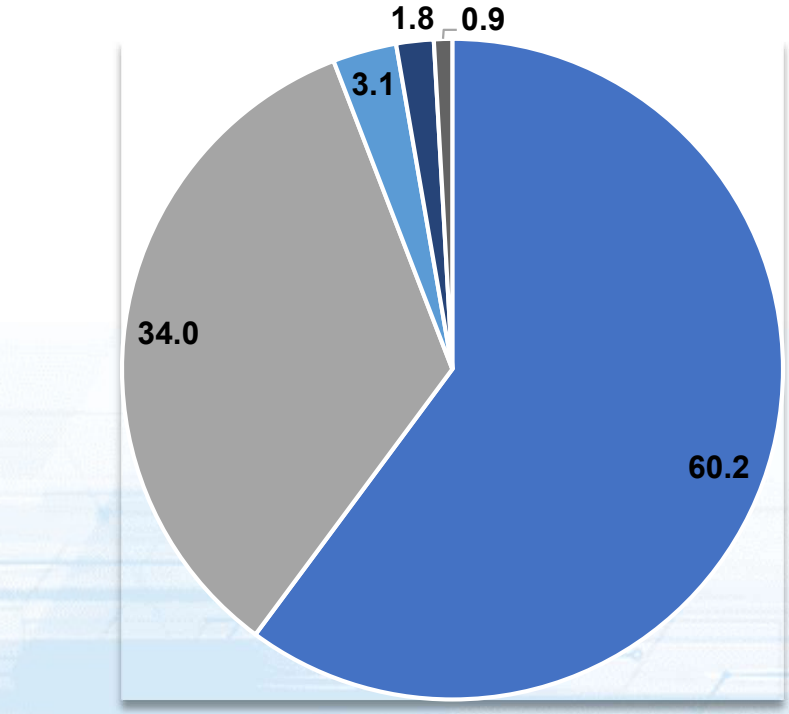


Trends in Composition of Equipment Net Sales by Shipping Destination

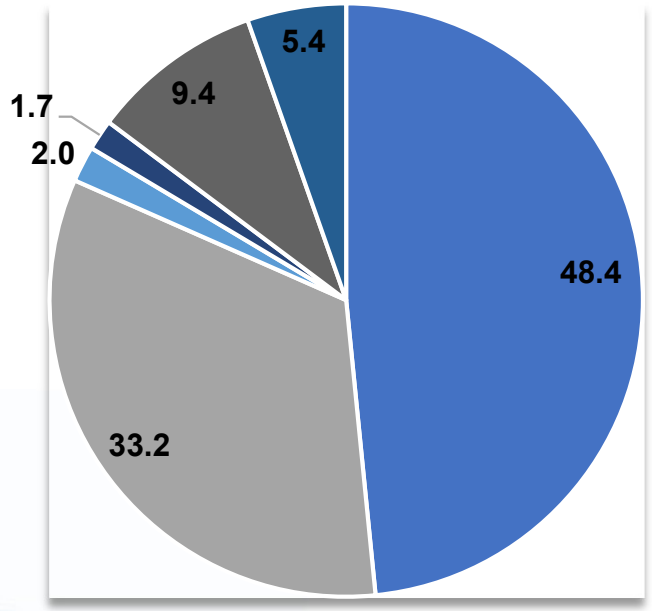


Trends in Composition of Net Sales by Region (1)
Comparison with the Fiscal year ended December 31, 2024

Recorded sales in the U.S. market (9.4% of total sales)



Fiscal year ended December 31, 2024, Unit: %



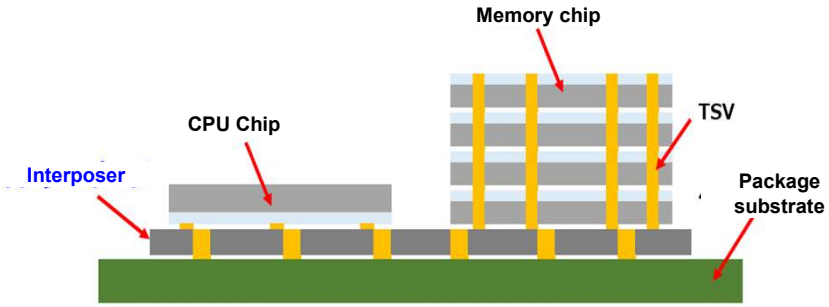
Six months ended June 30, 2025, Unit: %

U.S. subsidiary, Sales of Interposer Cleaning Equipment

Established a U.S. subsidiary JET AMERICA INC. in Texas in January 2024, where Texas Instruments (TI) and other companies are headquartered.
While beginning to develop customers in a legacy semiconductor area, orders for cleaning equipment for "interposers," which electrically connect semiconductor chips and substrates, have been received and shipped with local delivery and start-up has been completed in June 2025.

Interposer (Wiring circuit board)

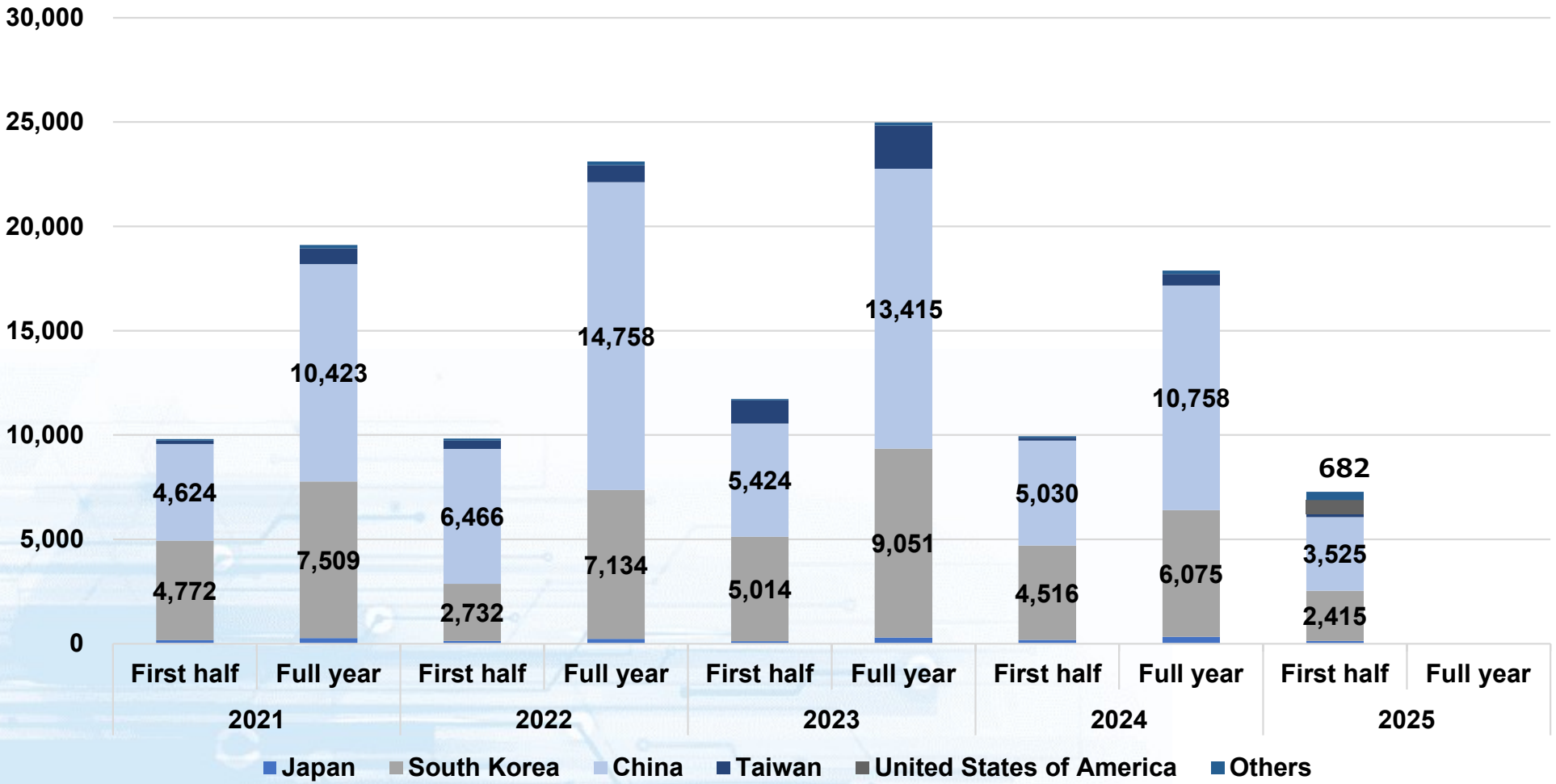
Originated from Latin, meaning "put in between."
A component that plays an extremely important role as a relay component in the technology of assembling semiconductor chips like Lego blocks (chiplet).
Essential for 2.5D and 3D packages, which will be the basic structure for advanced packaging of AI semiconductors.



JET AMERICA INC.

Trends in Composition of Net Sales by Region (2)

U.S. sales 682 million JPY; focuses on further market development in the future



Fiscal Year Ending December 2025, Full-Year Market Environment Outlook

While the macro environment remains challenging, there are signs of gradual improvement due to the transition to a data-driven society, including the expanded use of generative AI and the development of DX.

- ✓ **Although Japan, South Korea, the EU, and other countries have agreed on tariff measures by the U.S., the impact on the global economy is still unclear as confirmation of agreed items is yet to be completed and the new tariff rates are considerably high even though they have been reduced from those originally proposed.**
- ✓ **Concerns persist over China's economic stagnation stemming from the U.S.-China trade friction and real estate downturn.**
- ✓ **As the transition to a data society continues, the need for advanced semiconductors is further increasing.**
- ✓ **Demand for legacy semiconductors for automotive and industrial applications is weak but moderately improving.**

Full-Year Forecast for the Year Ending December 31, 2025 (1)

Revised full-year forecast: Forecast for this fiscal year is in the red.

Net sales	Operating profit	Ordinary profit	Net profit
13,420 million JPY	-1,810 million JPY	-1,910 million JPY	-2,750 million JPY
YoY -24.9%	YoY -	YoY -	YoY -

Factors behind decrease of revenue

- Startup of cleaning equipment for Korean memory makers and Chinese foundries rescheduled to the next fiscal year.
- Investment plans for equipment for which orders had been expected from Chinese foundries and memory manufacturers were postponed.

Full-Year Forecast for the Year Ending December 31, 2025 (2)

Inventory of products for which orders have been received but delivery dates are not clear is liquidated as an inventory valuation loss.

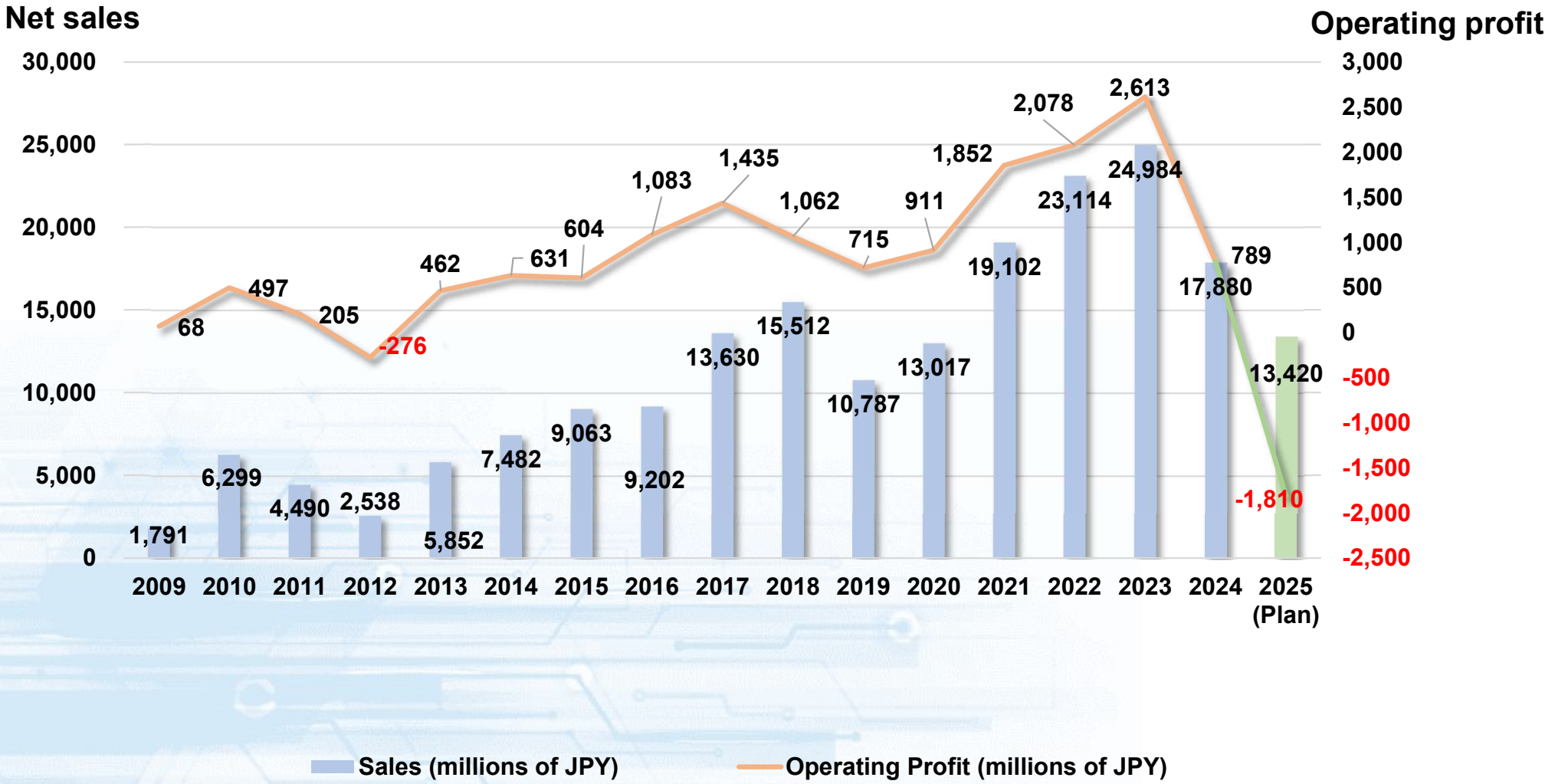
Causes of a decrease in profit

- Sales declined significantly due to the failure to win orders for projects in the Chinese market, which had been expected in the first half of 2025.
- Recorded sales of low-margin equipment ordered in competition with local manufacturers in the Chinese market.
- Recorded an inventory valuation loss of products, which amounts to 1,340 million JPY.
- Recorded an inventory valuation loss of parts, which amounts to 200 million JPY.
- Recorded income tax adjustments due to reversal of deferred tax assets (760 million JPY)

2. Revision of Management Strategy in Response to the Revised Financial Results

Trends in the Long-Term Consolidated Results (Net Sales and Operating Profit)

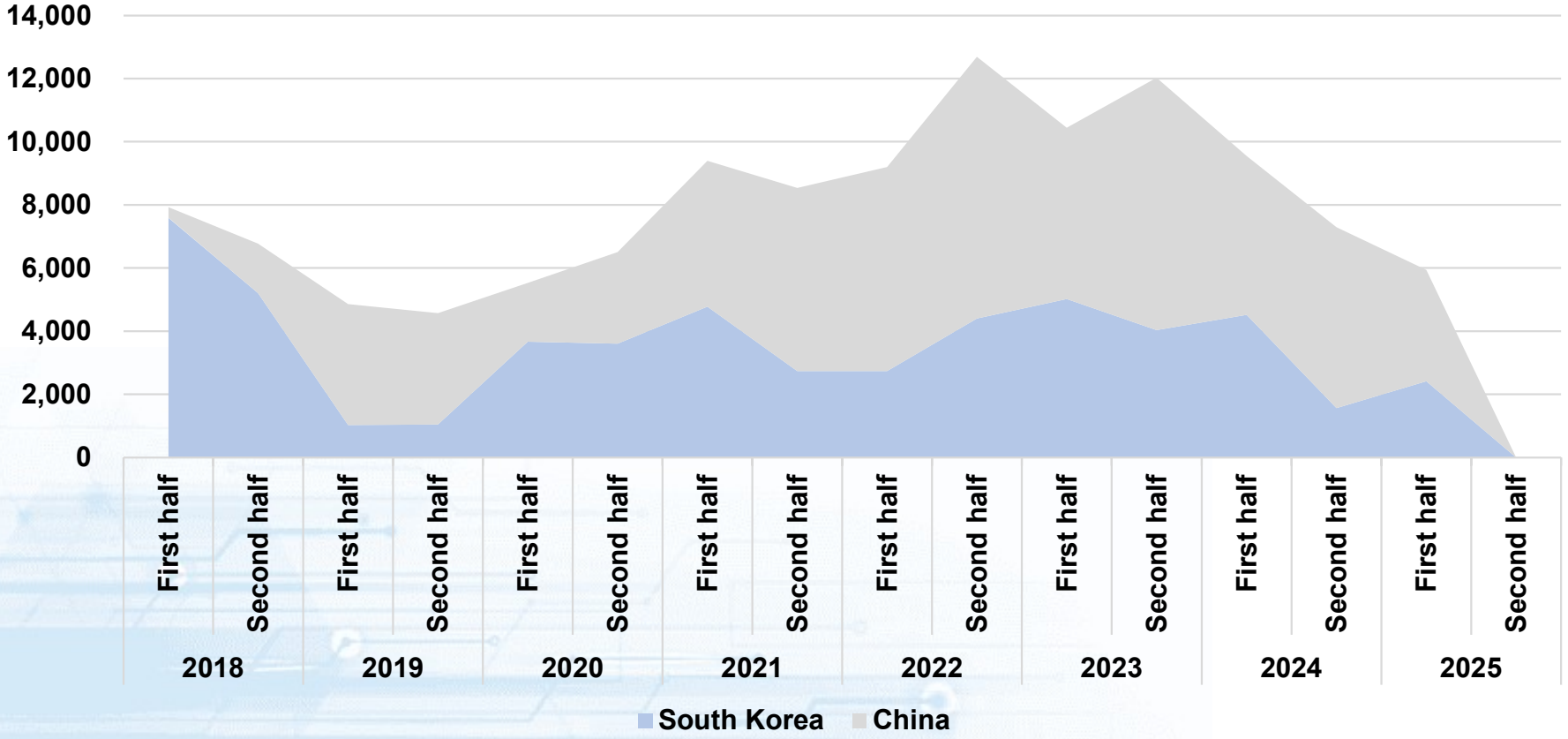
With this revision, both net sales and operating profit slump to 2020 levels.
Operating profit is in the red for the first time since 2012



Note: Figures for 2019 and therebefore are unaudited by an audit firm and are provided for reference only

Sales in China and Korea, Up and Down Trend

The Chinese market drove performance from 2021 to 2023.
Stagnation of the Chinese market and the intensification of the competitive environment are the reasons for the tough situations in the second half of 2024 and beyond.



	2018		2019		2020		2021		2022		2023		2024		2025	
	First half	Second half	First half	Second half	First half	Second half	First half	Second half	First half	Second half	First half	Second half	First half	Second half	First half	Second half
South Korea	7,594	5,208	1,024	1,046	3,667	3,602	4,772	2,737	2,732	4,402	5,014	4,037	4,516	1,559	2,415	
China	330	1,568	3,832	3,528	1,856	2,899	4,624	5,799	6,466	8,292	5,424	7,991	5,030	5,728	3,525	

Current Status of the Chinese Market and Future Measures

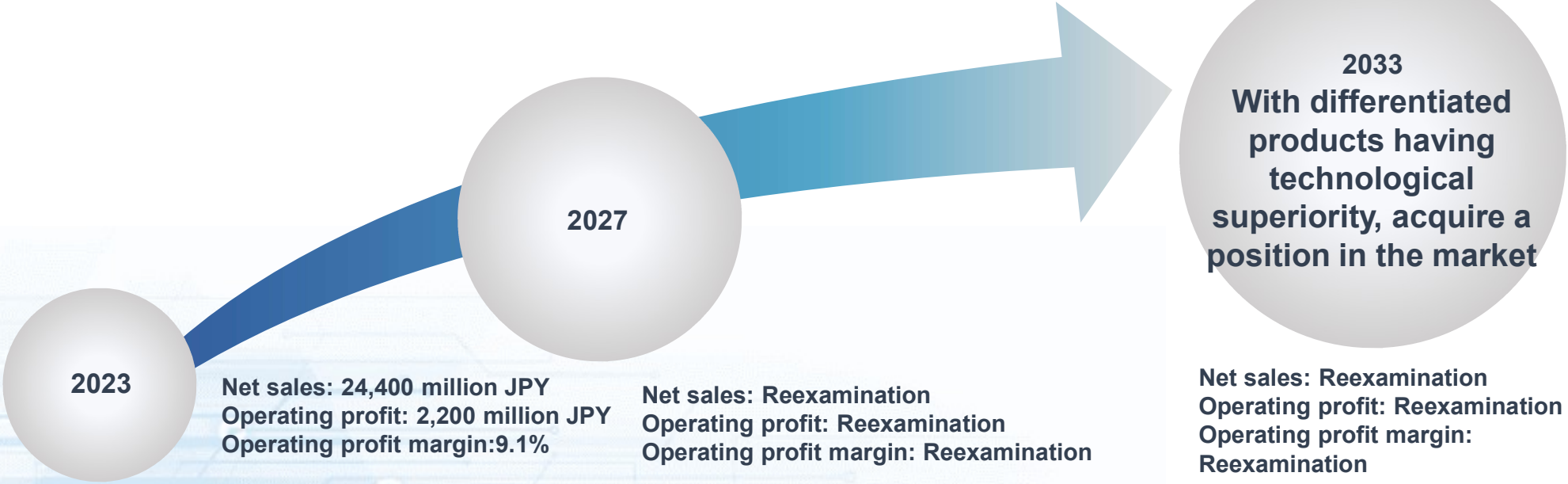
- In the midst of the conflict between the U.S. and China, the semiconductor industry has recently been strengthened as a national policy, with the aim of becoming self-reliant.
- Strong new capital investment has been implemented, especially for mature semiconductors.
- Decline in facility utilization rates as a reaction to rapid facility expansion, and postponement of investment plans, etc., became apparent.
- Emerging Chinese manufacturers have expanded their share in the cleaning equipment market as well, backed by the state, thereby intensifying the competition.
- Currently, the emerging Chinese manufacturers are considering to advance into the global market, outside the market of their own country.

- As for the batch-type tools, we are focusing on switching from the BW3000, our mainstay model, to its successor, the BW3500.
- The BW3500 is a strategic model that targets the process of 28nm and larger, which is the focus of investment for the years ahead, with technological advantages over local manufacturers, while also intending to replace Japanese competitors' products.
- Currently, while we are responding to inquiries in China, we are exposed to the threats by emerging Chinese manufacturers with the backdrop of political pressure.

- **While promoting sales of BW3500, we also seek collaboration and cooperation with other companies flexibly, rather than operating solely in China, to realize local manufacturing thereby making it a Chinese product.**

Revision of Medium- and Long-Term Management Strategies

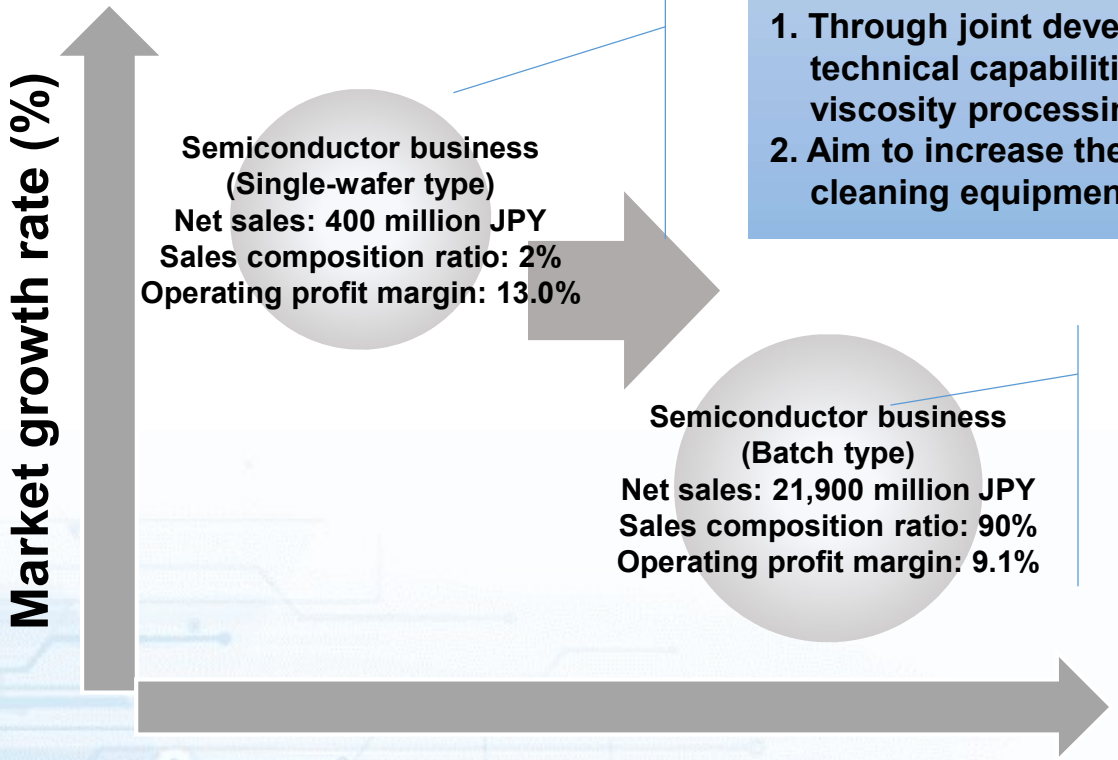
In response to the revisions to the financial results, which were based on an objective view of the market environment, we began "reviewing and reconsidering" our numerical targets and the four axes of "Product Strategy," "Area Strategy," "Human Capital Strategy," and "Manufacturing Strategy" in light of the current situation although the major strategic direction will remain unchanged.



Product Strategy	Area Strategy	Human Capital Strategy	Manufacturing Strategy

Business Portfolio Reorganization

While maintaining market share of batch-type equipment, continue to pursue growth with differentiated single-wafer cleaning equipment.



1. Through joint development with Rapidus, promote the technical capabilities of high-temperature, high-viscosity processing
2. Aim to increase the market share by developing cleaning equipment that does not use sulfuric acid, etc.

Expand into the Japanese and U.S. markets in addition to major markets while promoting high customizability

* Figures are actual results for FY2023

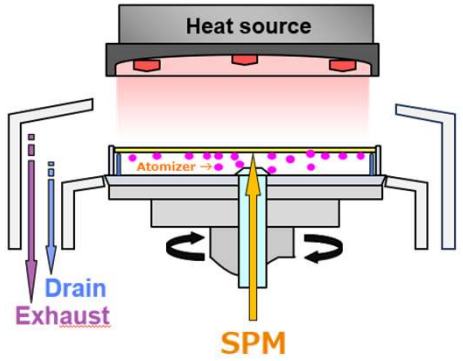
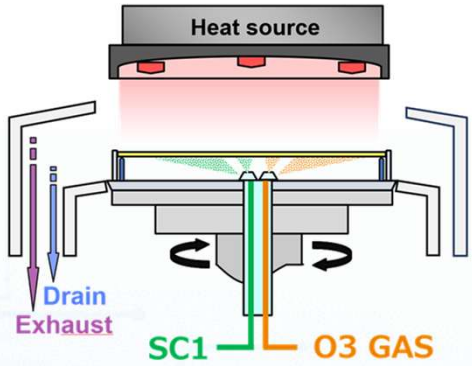
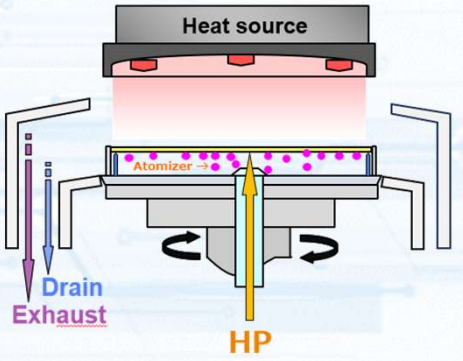
- The market for batch-type cleaning equipment is expected to maintain a certain market size and grow moderately in line with the growth of the semiconductor market.
  We have an 11% share of the global market and aim to continue to expand the market share ratio.
- Single-wafer cleaning equipment is likely to remain the primary cleaning equipment in the future and the market is expected to grow significantly with the growth of the semiconductor market.
  We aim to expand our market share through the development and sale of single-wafer cleaning equipment capable of high-temperature, high-viscosity processing.

Joint Development with Rapidus, Delivered One Mass-production Machine

- Rapidus entered a strategic partnership with IBM for the development and production of 2-nm semiconductors.
- Rapidus aims to achieve semiconductor manufacturing “faster than any other companies” in high-mix, low-volume production with a focus on using only single-wafer-type tools
- Manufacturing equipment is basically from IBM’s line; however, for the phosphoric acid etching process, IBM’s line does not have a single-wafer-type tool, which requires separate development.
- Completed the research and development phase (α machine), the project was in the research and development phase (β machine) related to the production of prototype equipment. We delivered a mass-production machine in July 2025.
- We continue to support the mass-production lines planned for 2027.

Rapidus Chitose Plant (IIM)
Construction started in September 2023
Prototype line starts operation in April 2025
2-nm semiconductor prototype released in July 2025
Mass production line scheduled to start up in 2027

Different processes of the J.E.T. Single-Wafer-Type Equipment

Type of chemicals	JET's Equipment	Illustrative drawings	Features and Performance
SPM(H2SO4) Resist stripping after high dose implantations Resist stripping after dry etching of P-SiN	**HTS** HTS-300		**Reduction of used chemical amount** Reduces the amount of chemicals to 1/20 compared with competitors through significant shortening of process duration High resist stripping rate is achieved with temperature controlled by heater Enables efficient processing Suppress particle generation due to free falling of the removed resist
O3 GAS Resist stripping after high dose implantations Resist stripping after dry etching of P-SiN	**EcO3** OMR-3000		**Less environmental impact as well as low running costs** Leveraging the structure of single-wafer-type SPM tools, processing with O_3 gas has been realized. Using O_3 gas enables a process similar to SPM while mitigating the environmental impact SC1 treatment in a single process module is possible since no by-products are formed by reaction of acids and alkalis.
HP(H3PO4) Removal of front side SiN	**Rush** HPR-3000		**First ever high temperature, high etching rate process with a single-wafer-type tool** JET's patented technology enables state-of-the-art nitriding film processing in a single-wafer-type tool. High wafer uniformity is realized High etching rate is achieved by maintaining high temperatures
HP(H3PO4) Removal of back side SiN	**Rush** HBE-3000		

Patent: No. 5079145, No. 5165131

Direction of Product Strategy Remains Unchanged

We will continue to focus on the development of single-wafer cleaning equipment that leverages the advantage of our technological superiority while re-examining the details.

New HTS

1. **Capability of handling processes other than sulfuric acid**
2. **Different product models offered for different chemical solutions (processes)**
3. **Lateral expansion of phosphoric acid based on track record in Japan**
4. **Responding to new inquiries on O_3 (Ozone)**

2033
With differentiated products having technological superiority, acquire a position in the market

Postponement of Construction of New Plant and Renovation of Main Plant (1)

Background and objectives of the subsidized project

(1) Production capacity issue:
The Head Office Plant, which has been repeatedly expanded and remodeled, is becoming too small and is running out of production capacity

(2) Productivity issue:
- The number of parts required to manufacture one unit of cleaning equipment is 20,000 to 30,000. With increase in production volume, conventional use of manual labor for storage, management, and picking has become inefficient.
- Leasing of an outside warehouse to address lack of space for storing parts at the Head Office Plant has led to increased costs.

(3) R&D issue:
Chemicals, etc., are available to only one experimental tool. Multiple experiments cannot be carried out concurrently. (Causing slower response to customers and development)

- Plans to construct a new plant to solve the above issues
- Selected for the Ministry of Economy, Trade and Industry's "Subsidy Program for Large-Scale Growth Investment in Labor-Saving and Other Measures to Raise Wages for Small and Medium-Sized Enterprises."

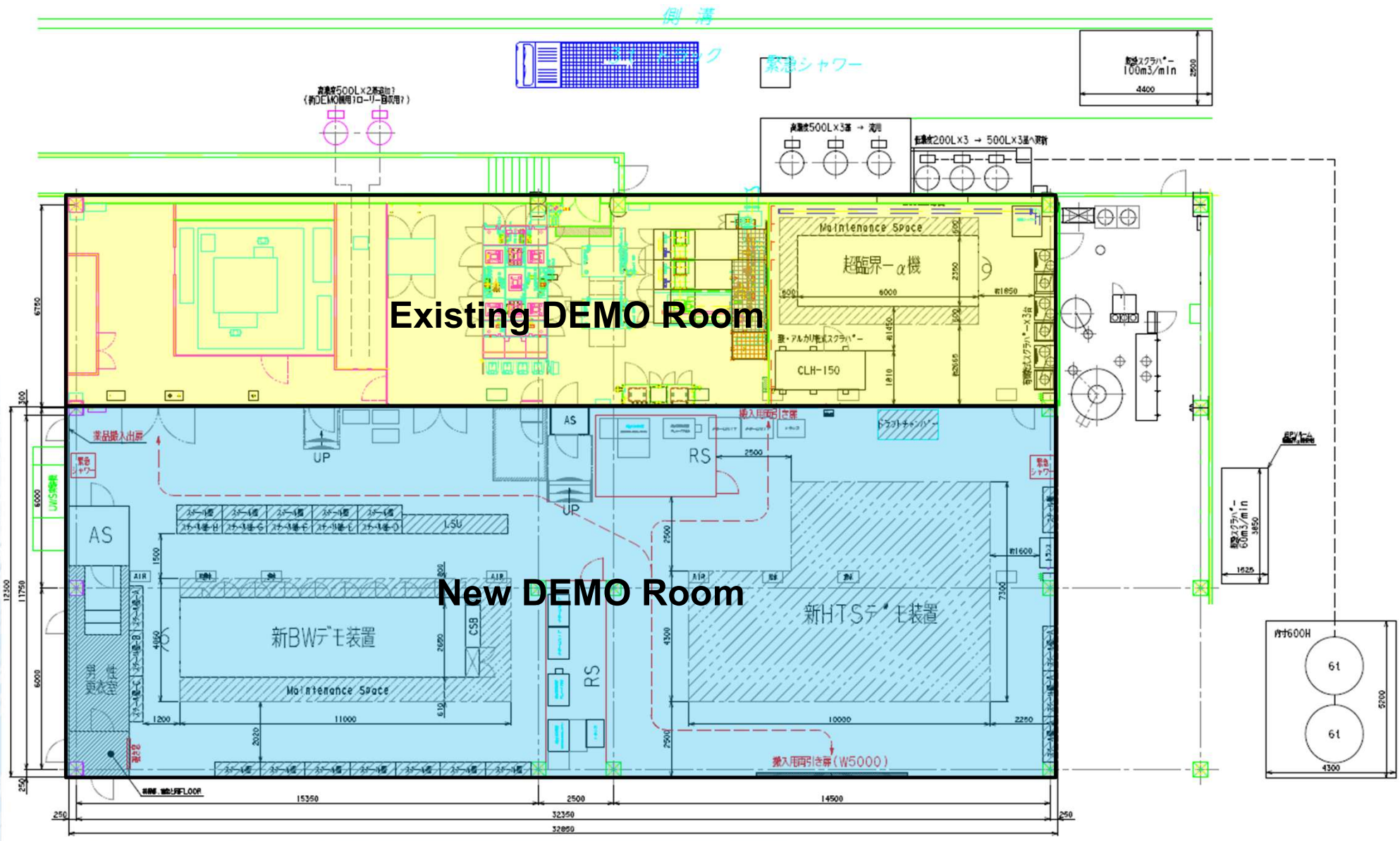
- **Although a site has been secured in Asakuchi City adjacent to the current head office, the construction of a new plant is still under consideration in light of the current situation.**
- **However, to accommodate issue (3) and demonstrations for customers, the decision was made to expand and renovate the current plant.**
- **The expansion and renovation itself falls under the subsidy approved project.**

Postponement of Construction of New Plant and Renovation of Main Plant (2)

Scope of the expansion and renovation

Purpose	Concrete details		Department in charge	Schedule
(1) Rapid response to DEMOs requested by customers, improve credibility (2) Acceleration of new product development	Convert C/R 14&15 Booth to DEMO rooms		Technology Development Dept. (General Affairs Dept.)	Under adjustment targeting late 2026
	Increased DEMO capacity	Installation of new compressors		
		Expansion of pure water facilities		
		Installation of new scrubbers		
		Installation of new liquid waste treatment facilities		
	Installation of New BW DEMO equipment		SD Dept. (SE Dept., Procurement Dept.)	
	Installation of new HTS DEMO equipment			
(3) Improving the work environment (Measures against aging)	Measures against leakage of rain		General Affairs Dept.	
(4) Equipment reinforcement (Measures against aging)	Replacement of hoists at loading and unloading ports		Procurement Dept. (General Affairs Dept.)	

Postponement of Construction of New Plant and Renovation of Main Plant (3)



Appendix

Company Overview

Engaged in development, manufacture, sales, and after-sales service of semiconductor cleaning equipment

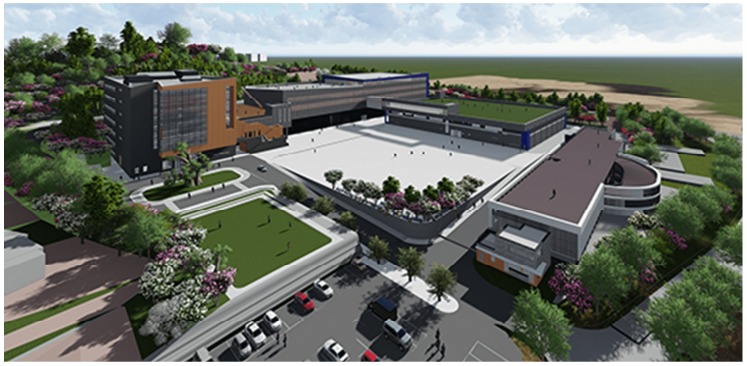
Our forerunner was S.E.S. Co., Ltd. (“S.E.S.”), which commenced civil rehabilitation proceedings during the semiconductor recession in the aftermath of the collapse of Lehman Brothers and subsequently went into bankruptcy
To take over S.E.S.'s outstanding technologies for semiconductor cleaning equipment, we were established on April 24, 2009 as a wholly owned subsidiary of ZEUS CO., LTD. ("ZEUS"), a Korean company that was a sales agent of S.E.S. In May 2009, we launched our business as we acquired S.E.S.'s Okayama Plant, etc., in a business transfer

■ Company Overview

Name	J.E.T. Co., Ltd.
English Name	J.E.T. Co., LTD.
Establishment	April 2009
Capital	1,848 million JPY (as of December 31, 2024)
Address TEL	6078, Shinjo Kanayama, Satosho-cho, Asakuchi-gun, Okayama 0865-69-4080
Representative	Masayuki Bouno, Representative Director and CEO
Number of Employees	163 employees 279 employees, * Total number of employees including consolidated subsidiaries (as of June 30, 2025)
Business summary	Development, manufacture, sales and after-sales service of semiconductor cleaning equipment
Main Customers	Samsung Electronics (South Korea), SMIC (China)

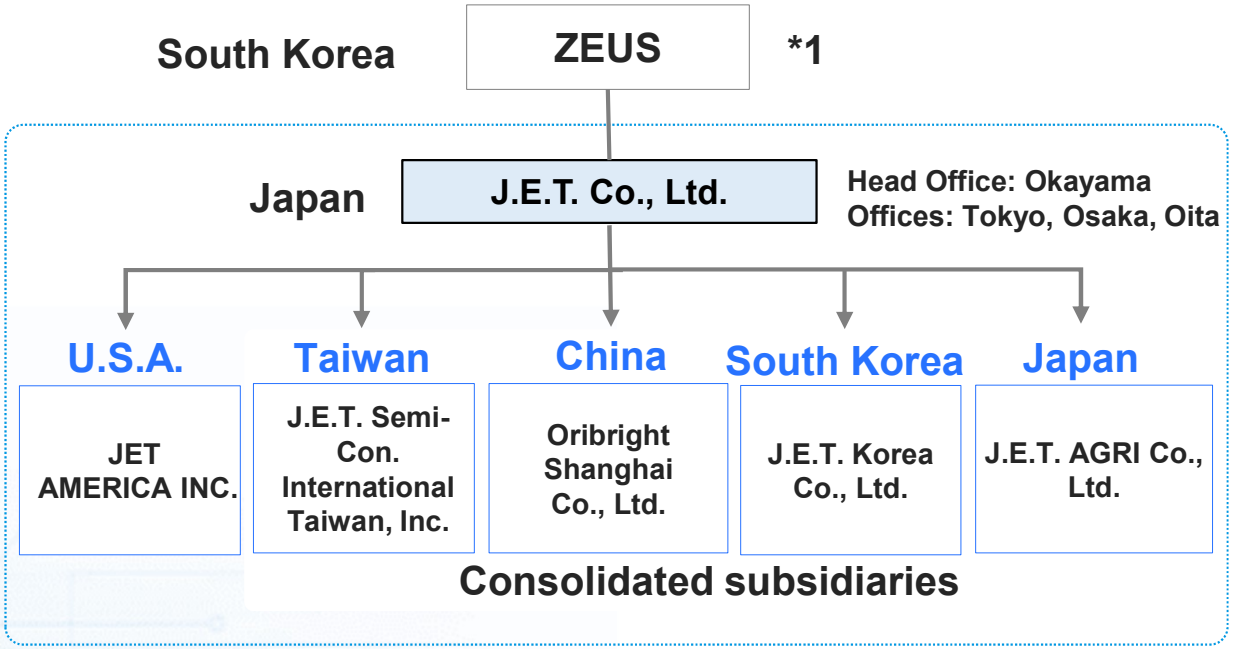
Group Relationship Diagram

Our business is separate from that of ZEUS, our parent company. We have no competitive relationship with them, and our management aims to be highly independent of them by eliminating the acceptance of officers and employees on secondment.



Address: Hwaseong City, Gyeonggi Province, Republic of Korea
Capital: 15,530,995 thousand KRW
Description of business:
Manufacture and sales of various manufacturing equipment for semiconductors and liquid crystal
Percentage of voting rights held in our company:
66.3% (direct)
Relationship with the related party: Business transactions
Description of transactions:
Sales and purchase of parts, materials, etc., and outsourcing of equipment manufacturing operations between the two companies, and payment of sales commissions, etc., from us to ZEUS

Relationship Diagram



*1: Listed on KOSDAQ (a stock exchange in South Korea)

Note: Until the end of April 2022, we had one part-time director from ZEUS. From May 2022 onward, we have no officers or employees on secondment or otherwise accepted from ZEUS.

Offices

- Offices in Japan
- Offices outside Japan

Office in South Korea: 19 employees

J.E.T. korea Co., Ltd.

Oribright Shanghai Co., Ltd. Beijing Office

Oribright Shanghai Co., Ltd. Wuxi Office

Oribright Shanghai Co., Ltd. Hefei Office

Oribright Shanghai Co., Ltd. Xi'an Office

Oribright Shanghai Co., Ltd. Guangzhou Office

Oribright Shanghai Co., Ltd. Shanghai Head Office

Offices in China: 69 employees

Note: Some offices in China have been omitted.

Osaka Office (*2)

Tokyo Office (*1)

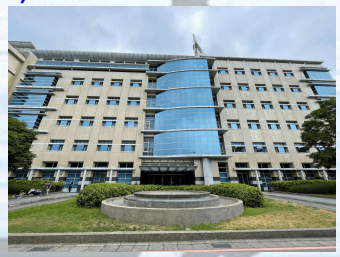
J.E.T. Co., Ltd.

Kyushu Branch (*1)

- Head Office
- Kasaoka Farm (*1)

Head Office (Okayama)

J.E.T. Semi-Con. International Taiwan, Inc.
(HEAD Office) Taiwan Head Office



Office in Taiwan: 21 employees

J.E.T. Semi-Con. International Taiwan, Inc.
(Singapore branch) Singapore Branch

Singapore: 3 employees

JET AMERICA INC.

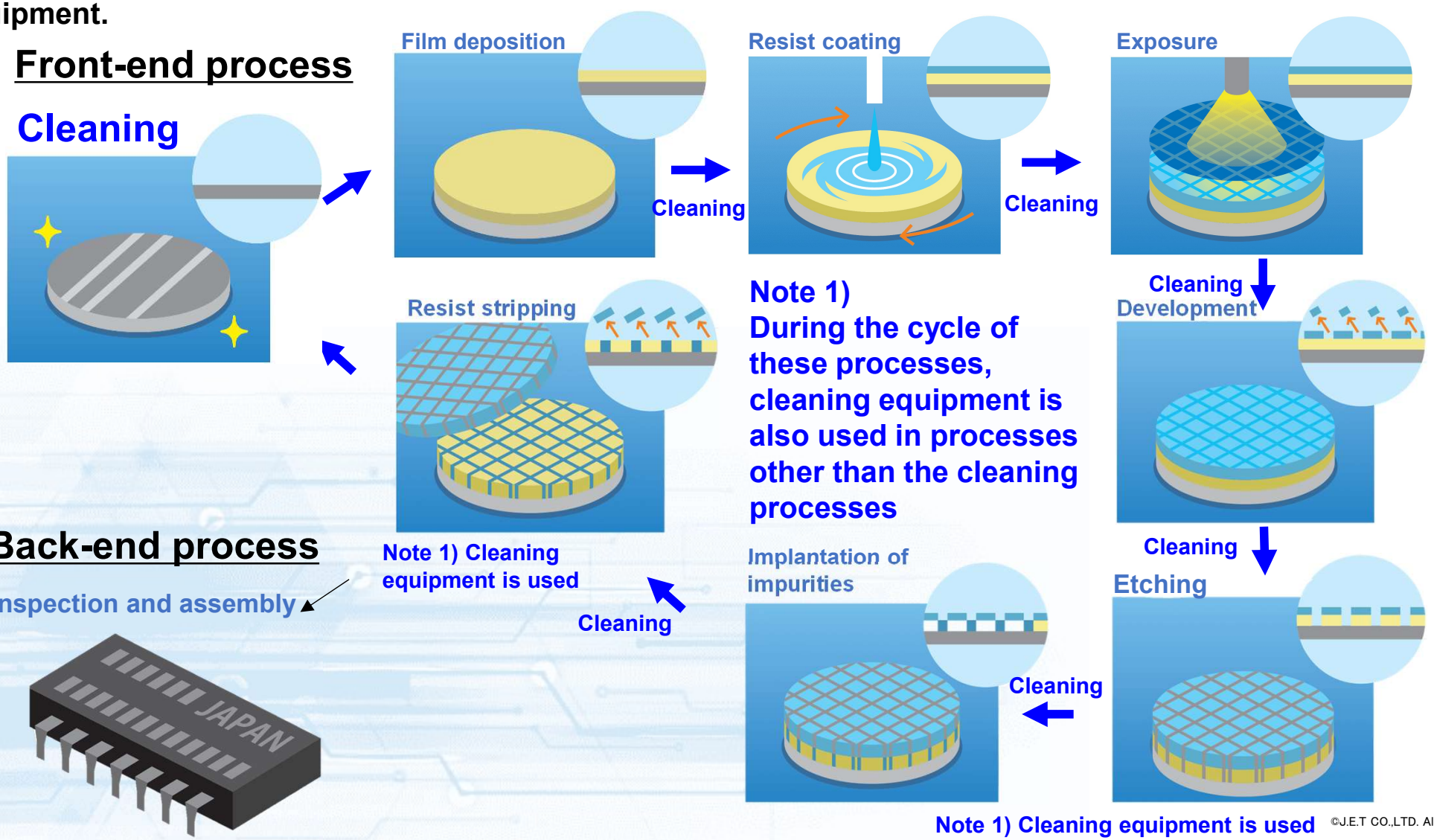
Office in the United States: 3 employees

*1 At Tokyo Office and Kyushu Branch, we provide field services to our customers.
*2 Osaka Office is in charge of LIB product sales.
*3 At Kasaoka Farm, J.E.T. AGRI Co., Ltd., our consolidated subsidiary, grows tomatoes.

Semiconductor Manufacturing Process
Front-end Process

Cleaning is extremely important in the front-end process (which includes more than 500 steps) of semiconductor manufacturing.
30–40% (based on the number of steps) of the front-end process is estimated to involve the use of cleaning equipment.

Front-end process

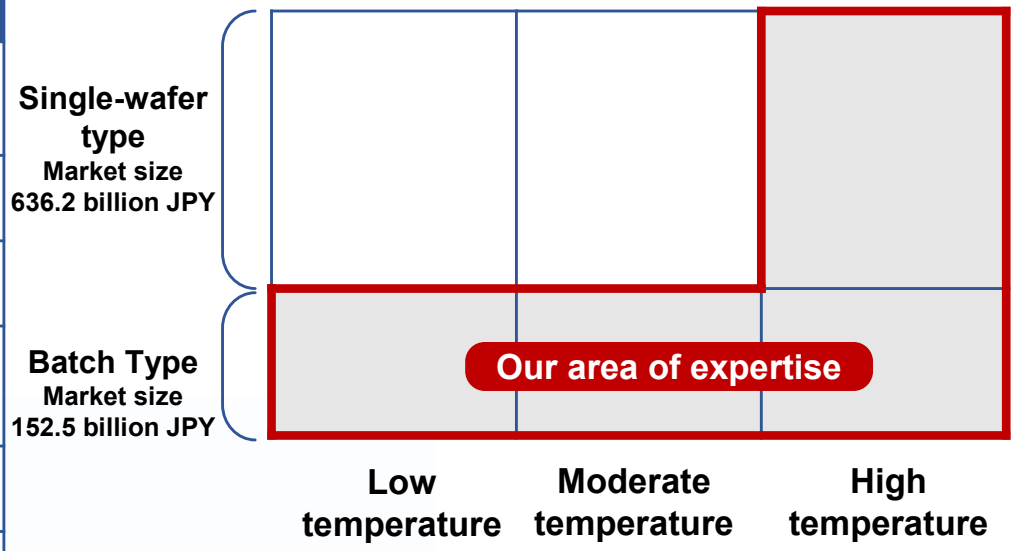


Note 1) Cleaning equipment is used

Semiconductor Cleaning Equipment Batch Type and Single-Wafer Type—Our Area of Expertise

		Batch-type cleaning equipment	Single-wafer-type cleaning equipment
Summary		25 to 50 wafers are batch-cleaned	Cleans wafers one by one
Advantage		It is highly productive	Precision cleaning is possible
Disadvantage		It can easily pick up wafer dust	It causes low productivity
Current status		Due to its superior productivity, maintains a certain share	Currently the mainstream cleaning equipment
High-temperature, high-viscosity processing	Features	Easy to maintain process temperature	Difficult to maintain process temperature
	Sulfuric acid	++ (mainstream)	+ (partially supported)
	Phosphoric acid	++ (mainstream)	- (not supported)
Market size (2023/Global)		152.5 billion JPY (J.E.T.'s share: 14.3%)	636.2 billion JPY (J.E.T.'s share: 0.1%)

* J.E.T.'s share...Batch type: 14.3%, Single-wafer type: 0.1%



Competitive Landscape and Differentiators

We believe that Japanese companies have had more than a 70% share in the semiconductor cleaning equipment market since the 2000s, and Company A and Company B have a particularly strong presence

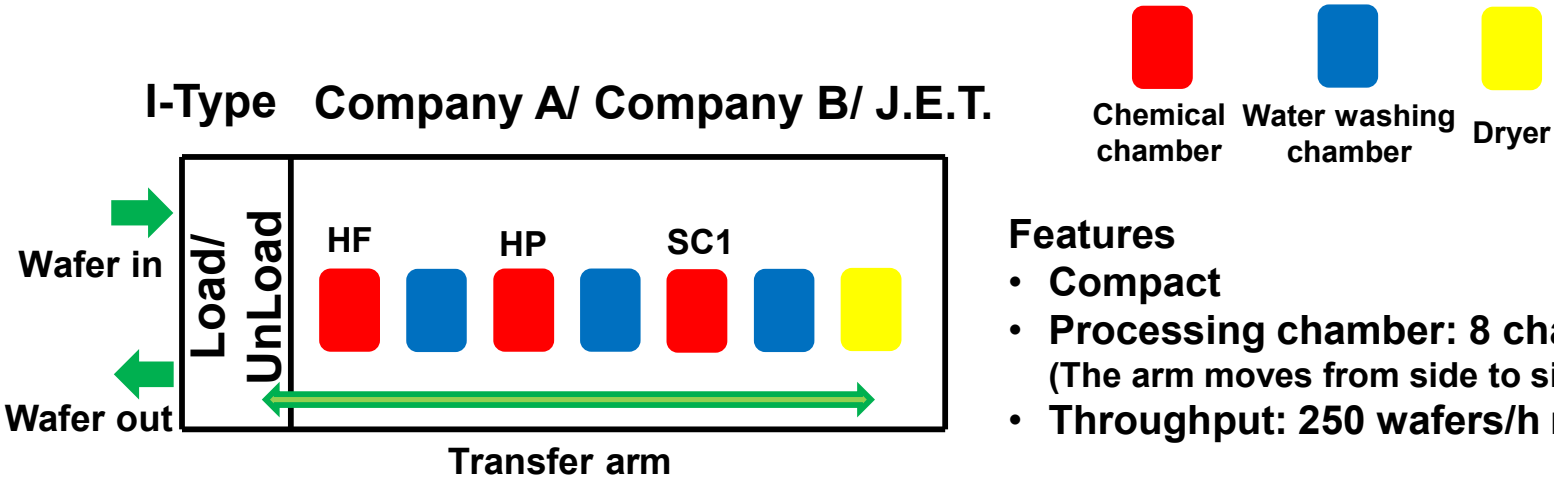
		J.E.T.	Company A	Company B
Company Size (Net sales/operating profit in FY2023)		25.0 billion JPY (2.6 billion JPY)	504.9 billion JPY (94.1 billion JPY)	1,830.5 billion JPY (456.2 billion JPY)
Market Share (Market Size in FY2023)	Batch type (152.5 billion JPY)	14.3% (21.8 billion JPY)	49.3% (75.2 billion JPY)	21.6% (32.9 billion JPY)
	Single-wafer type (636.2 billion JPY)	0.1% (0.4 billion JPY)	47.3% (300.7 billion JPY)	20.7% (131.8 billion JPY)
Technologies	RCA Cleaning (hydrofluoric acid/ammonia water addition)	+	+++	++
	Sulfuric acid cleaning	+++	++	+
	Phosphoric acid cleaning	+++	++	+
	Others	++	+	++
Production Capacity		+ (Mass production capacity low)	+++ (Mass production capacity provided)	+++ (Mass production capacity provided)
Customizability		+++ (Strength in customizability)	+ (Strength in standardized equipment)	+ (Strength in standardized equipment)

Source: Ministry of Economy, Trade and Industry “Strategy for Semiconductors and the Digital Industry, June 2023”; evaluation is based on our own recognition

- Our competitors are large companies with sales in the hundreds of billions of JPY to trillions of JPY and their strength lies in their ability to mass produce high-quality, standardized equipment
- Although we lack mass production capacity, we entered into a niche market area, which larger companies would have difficulty accessing, involving complex high-temperature and high-viscosity processing with highly customizable tools leveraging our flexible operational abilities, and have obtained a share of the market.

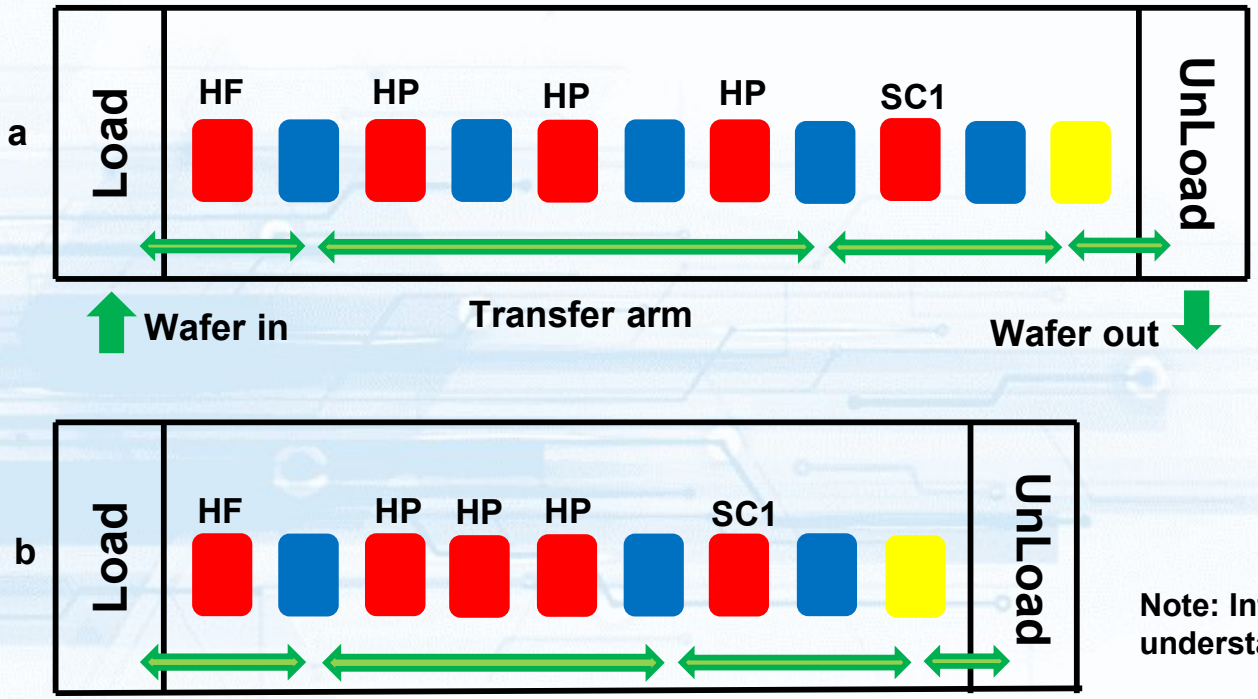
JET batch-type equipment advantages
➡ The only equipment with F-Type

I-Type Company A/ Company B/ J.E.T.



Features
- Compact
- Processing chamber: 8 chambers max.
  (The arm moves from side to side, causing jams)
- Throughput: 250 wafers/h max.

F-Type Made by J.E.T. only



Features
- A little large
- Processing chamber: 14 chambers max.

(Because the one-way arm prevents jams)
- Can be selected from a or b
- b enables sequential arrangement of chemical chambers
- Often used for sulfuric acid/phosphoric acid cleaning at high temperatures
- Throughput: 500 wafers/h max.

Note: Information is based on our own understanding as of December 2023.

Our Main Products (1)

	BW3000	BW3700
		
Cleaning type	Batch-type cleaning equipment Compatible with 300-mm wafers	Batch-type cleaning equipment Compatible with 300-mm wafers
Features	◎Flexible configuration to meet customers' requirements (the arrangement and the number of cleaning chambers can be changed according to the customer's request) ◎Improvement in production efficiency ◎High-Speed LD/ULD compatible with 500 WPH ◎Small equipment footprint: The number of installations in a plant can be increased ◎Reduction in carbon dioxide ◎Controlled gas flow ◎Reduced start-up time by standardized specifications ◎Compatibility with SEMI standard ◎Compatibility with EES (in either EDA or TDI format)	◎Small equipment footprint: The number of installations in a plant can be increased ◎Stabilization of throughput of each processing chamber through individual piping in the exhaust system ◎Processing with a 7-mm pitch between wafers ◎Reduction in generation of particles (fine dust) by achieving a reduction of the contact point of wafers ◎Reduction in bubble generation ◎Improved efficiency in liquid replacement by a reverse flow system ◎Improved stability in concentration ◎Compatibility with a wide variety of processing chambers ◎Compatibility with the 1 chemical solution plus 1 DIW configuration
Price range (average unit price) (millions of JPY)	210–400	320–560

Our Main Products (2)

	BW2000	HTS-300
		
Cleaning type	Batch-type cleaning equipment Compatible with 200-mm wafers	Single-wafer-type cleaning equipment Compatible with 300-mm wafers
Features	◎High production efficiency ◎High cleaning capacity ◎Reduced footprint ◎Flexible configuration to meet customers' requirements (the configuration and the number of cleaning chambers can be changed.)	◎Processing with a minimum chemical solution consumption of 150 cc ◎High-temperature processing up to 240ºC ◎Stripping in as short as 30 seconds ◎Prevention of fume (chemical vapor) diffusion through wafer inversion processing
Price range (average unit price) (millions of JPY)	150–210	330–540

Our main products (3) BW3500

Twenty years have passed since the development of the mainstay BW3000 and BW3500 were developed as successor models to better meet customer needs

→ For processes of 28-nm and larger, which are the focus of investment for the years to come

→ Replacing competitors' products for RCA cleaning in mind

Improvements from BW3000

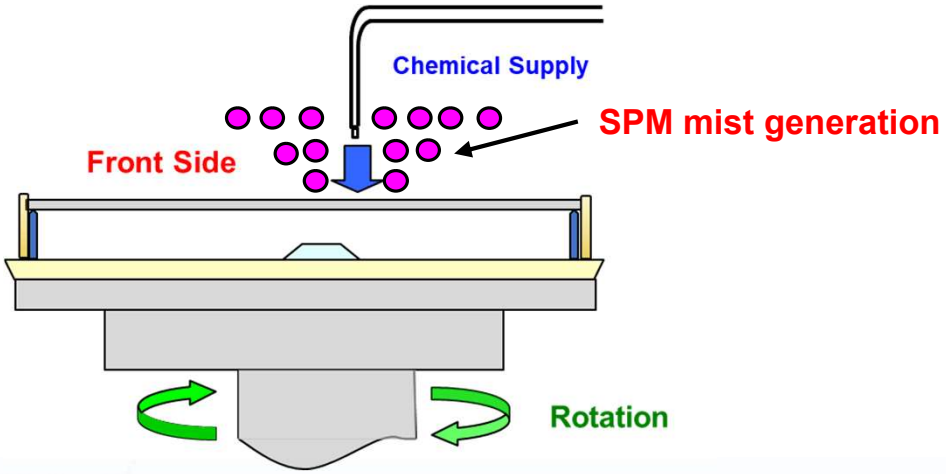
1. **Reduced footprint (15-16% reduction in equipment area and 20% reduction in overall equipment length)**
2. **Adoption of a new transfer method (Transfer by Moving/Single Lifter in addition to transfer arm)**
3. **Environmental and safety measures (Provision of dedicated OHT port and improvement of airtightness to reduce leaking out of chemical atmosphere)**
4. **Damage prevention measures (employment of resin tanks)**
5. **Improved operability (larger and colored operation screens, increased amount of information)**

In addition, one-bath processing, metal ion measures, new exhaust system, reduced chemical usage, improved throughput and a new drying system have been adopted

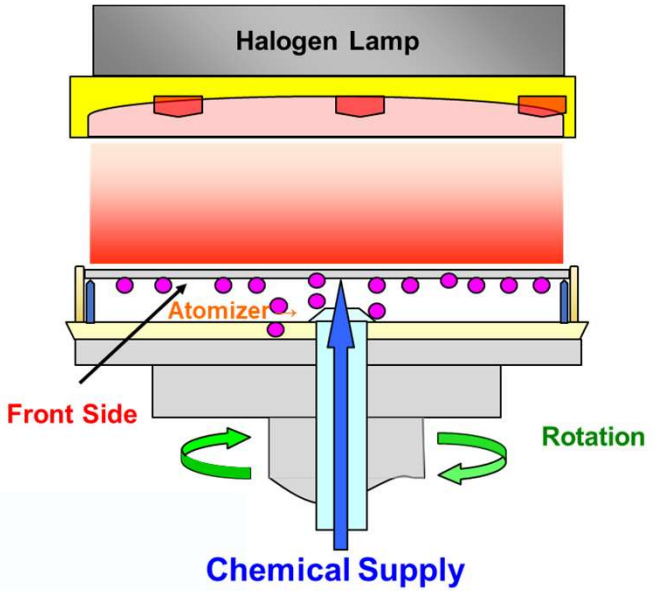
BW3500

Advantages of the J.E.T. Single-Wafer-Type Equipment

Company A/B single-wafer-type SPM system



J.E.T. single-wafer-type SPM system (HTS -300)



[Competitors' specifications]

- Uses heat of reaction of chemicals (150 to 200°C)
  - ➡ Difficult to maintain high temperatures even when continuously applying chemicals
- Process time: 5min/Wafer
  - ➡ Amount of required chemicals: 3,000 ml/Wafer (since continuous application of chemicals for 5 minutes is necessary)
- SPM mist generates more particles

[JET specifications]

- Raise the temperature with halogen lamps (200 to 240°C)
  - ➡ Easy to maintain high temperatures
- Process time: 0.5min/Wafer
  - ➡ Amount of required chemicals: 150 ml/Wafer (About 1/20 of the amount used by competitors)
- Turn the wafer over so that the processing surface faces downward before applying atomized chemicals to prevent diffusion of SPM mist thereby suppressing particle generation

Notes

Precautions for handling this document

- This document has been prepared based on the Consolidated Financial Results announced on August 8, 2025.
- The forecasts and forward-looking statements contained in this document are based on information currently available to us and do not guarantee or promise the accuracy or completeness of such information. In addition, changes in economic trends, industry competition, markets and systems may cause significant changes in the outlook.
- Figures in this document are rounded down to the nearest unit. Percentages are rounded off to the nearest unit.

For inquiries about this document, please contact:

J.E.T. Co., Ltd.
Corporate Management Division
TEL 0865-69-4281